

#### IN THE DRAWINGS

Applicants propose that Figures 1-6 be amended as indicated in red on the enclosed drawing sheets. More specifically, Figures 1, 2, 3A, 3B, 4A, 4B, 5 and 6 are amended to include the "prior art" designation as required by the Examiner. Further, Figures 1 and 2 are amended to correct the lead line corresponding to reference numbers "3" and "1", respectively. Lastly, the figure legends for Figures 3A, 3B, 4A and 4B are amended. Approval and substitution of the enclosed amended drawing sheets for the corresponding sheets presently on file are respectfully requested.

#### IN THE CLAIMS

Please amend Claims 1-3 as follows. A marked-up version of the amended claims is enclosed herewith, showing the changes made by the current amendment.

3 1. (Amended) A frame for semiconductor packages comprising plural lead frames arranged in a matrix through grid-leads, the grid-leads having terminals which project therefrom and terminals of adjacent pairs of lead frames are connected to one another at respective connection areas, semiconductor devices being respectively mounted on die-pads supported with suspending leads of individual lead frames, the semiconductor devices being collectively molded with molding compound, and the collectively molded semiconductor devices being cut along the grid-leads into individual semiconductor packages, wherein thin parts are formed adjacent roots of individual terminals, the terminal roots being disposed in the respective connection areas defined between interconnected pairs of terminals of adjacent lead frames.